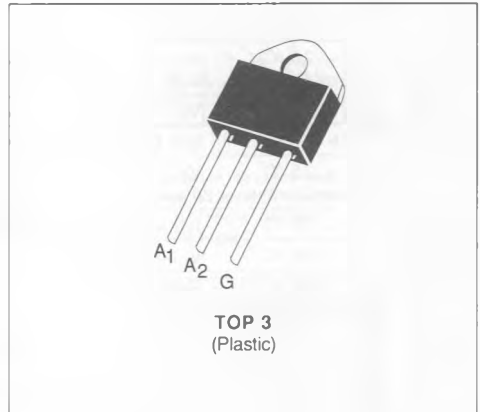




TRIACS

- GLASS PASSIVATED CHIP
- I_{GT} SPECIFIED IN FOUR QUADRANTS



DESCRIPTION

This new design of plastic uninsulated power triacs offers maximum efficiency with maximum ease of mounting.

ADVANTAGES

- NO TAPPING REQUIRED FOR FIXING
- EXCELLENT THERMAL IMPEDANCE AND HIGH RELIABILITY CONSTRUCTION

ABSOLUTE RATINGS (limiting values)

Symbol	Parameter		Value	Unit
I _{T(RMS)}	RMS on-state Current (360° conduction angle)	T _C = 80 °C	45	A
I _{TSM}	Non Repetitive Surge Peak on-state Current (T _j initial = 25 °C - Half sine wave)	t = 8.3 ms	315	A
		t = 10 ms	300	
I ² t	I ² t Value for Fusing	t = 10 ms	450	A ² s
di/dt	Critical Rate of Rise of on-state Current (1)	Repetitive F = 50 Hz	10	A/μs
		Non Repetitive	50	
T _{stg} T _j	Storage and Operating Junction Temperature Range		- 40 to 125 - 40 to 125	°C °C

Symbol	Parameter	BTB 41-					Unit
		200A	400A	600A	700A	800A	
V _{DRM}	Repetitive Peak off-state Voltage (2)	200	400	600	700	800	V

(1) I_G = 1.5 A di_G/dt = 1 A/μs

(2) T_j = 125 °C.

THERMAL RESISTANCES

Symbol	Parameter	Value	Unit
R _{th (j-a)}	Junction to Ambient	50	°C/W
R _{th (c-h)}	Contact (case-heatsink) with Grease	0.2	°C/W
R _{th (j-c) DC}	Junction to Case for DC	0.95	°C/W
R _{th (j-c) AC}	Junction to Case for 360 ° Conduction Angle (F = 50 Hz)	0.7	°C/W

GATE CHARACTERISTICS (maximum values)

$P_{GM} = 40\text{ W}$ ($t_p = 10\text{ }\mu\text{s}$) $I_{GM} = 10\text{ A}$ ($t_p = 10\text{ }\mu\text{s}$)
 $P_{G(AV)} = 1\text{ W}$ $V_{GM} = 16\text{ V}$ ($t_p = 10\text{ }\mu\text{s}$)

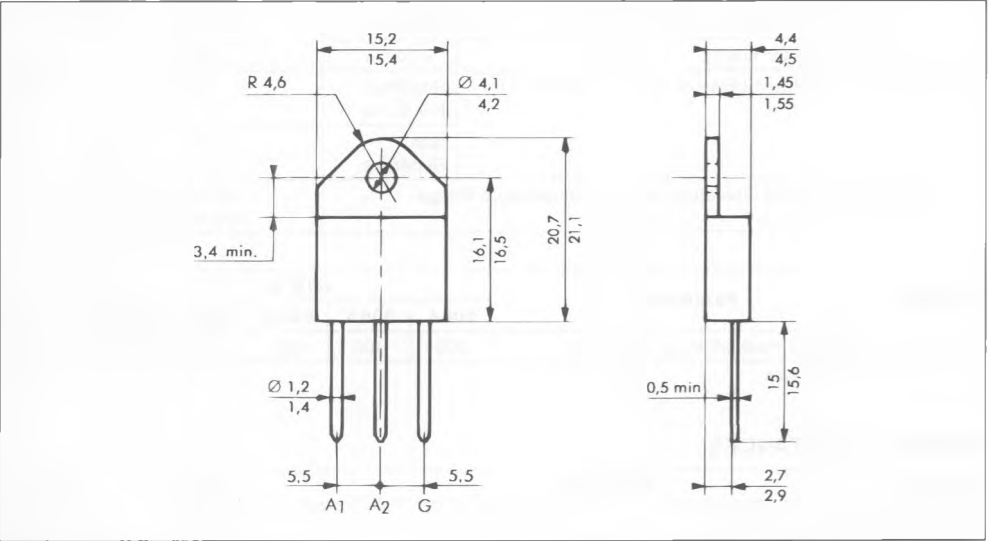
ELECTRICAL CHARACTERISTICS

Symbol	Test Conditions			Quadrants	Min.	Typ.	Max.	Unit
I_{GT}	$T_j = 25\text{ }^\circ\text{C}$ Pulse Duration $> 20\text{ }\mu\text{s}$	$V_D = 12\text{ V}$	$R_L = 33\text{ }\Omega$	I-II-III	1		100	mA
				IV	1		150	
V_{GT}	$T_j = 25\text{ }^\circ\text{C}$ Pulse Duration $> 20\text{ }\mu\text{s}$	$V_D = 12\text{ V}$	$R_L = 33\text{ }\Omega$	I-II-III-IV			1.5	V
V_{GD}	$T_j = 125\text{ }^\circ\text{C}$	$V_D = V_{DRM}$	$R_L = 3.3\text{ k}\Omega$	I-II-III-IV	0.2			V
I_H^*	$T_j = 25\text{ }^\circ\text{C}$	$I_T = 500\text{ mA}$	Gate Open			30	100	mA
I_L	$T_j = 25\text{ }^\circ\text{C}$ Pulse Duration $> 20\text{ }\mu\text{s}$	$V_D = 12\text{ V}$	$I_G = 300\text{ mA}$	I-II-III-IV			150	mA
V_{TM}^*	$T_j = 25\text{ }^\circ\text{C}$	$I_{TM} = 60\text{ A}$	$t_p = 10\text{ ms}$				1.8	V
I_{DRM}^*	$T_j = 125\text{ }^\circ\text{C}$	V_{DRM} Specified				1.5	6	mA
dv/dt^*	$T_j = 125\text{ }^\circ\text{C}$ Linear Slope up to $V_D = 67\text{ }\%$ V_{DRM}	Gate Open			250			V/ μs
$(dv/dt)_c^*$	$T_C = 75\text{ }^\circ\text{C}$ $(di/dt)_c = 20\text{ A/ms}$	$V_D = V_{DRM}$	$I_T = 60\text{ A}$		10			V/ μs
t_{gt}	$T_j = 25\text{ }^\circ\text{C}$ $I_G = 1\text{ A}$	$V_D = V_{DRM}$ $di_G/dt = 10\text{ A}/\mu\text{s}$	$I_T = 60\text{ A}$	I-II-III-IV		2.5		μs

* For either polarity of electrode A₂ voltage with reference to electrode A₁.

PACKAGE MECHANICAL DATA

TOP 3 Plastic



Cooling method : by conduction (method C)
Marking : type number
Weight : 5 g

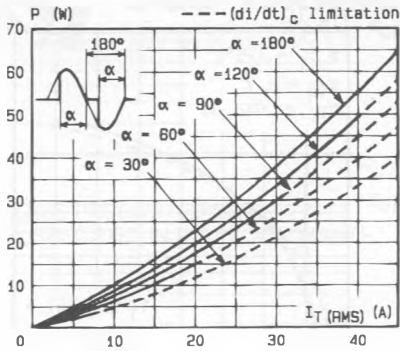


Fig.1 - Maximum mean power dissipation versus RMS on-state current ($f = 60$ Hz).

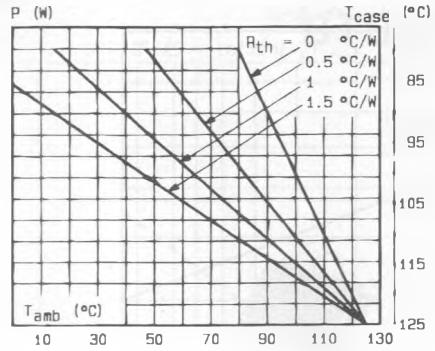


Fig.2 - Correlation between maximum mean power dissipation and maximum allowable temperatures (T_{amb} and T_{case}) for different thermal resistances heatsink + contact.

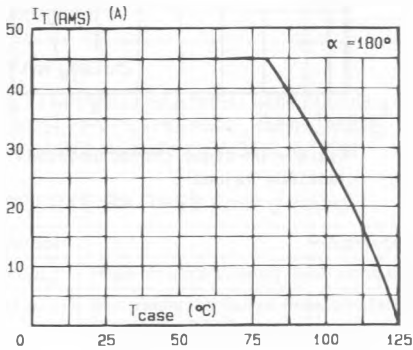


Fig.3 - RMS on-state current versus case temperature.

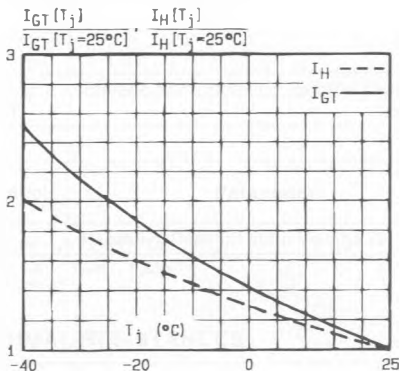


Fig.5 - Relative variation of gate trigger current and holding current versus junction temperature.

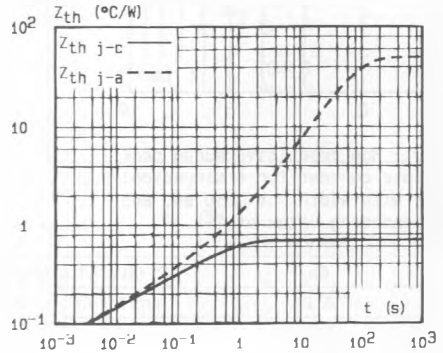


Fig.4 - Thermal transient impedance junction to case and junction to ambient versus pulse duration.

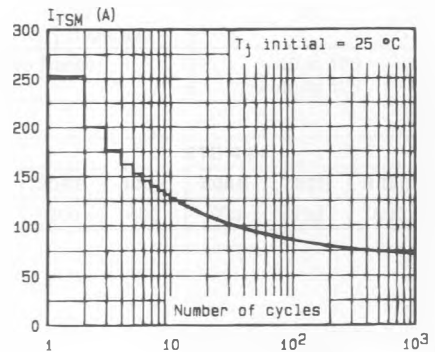


Fig.6 - Non repetitive surge peak on-state current versus number of cycles.

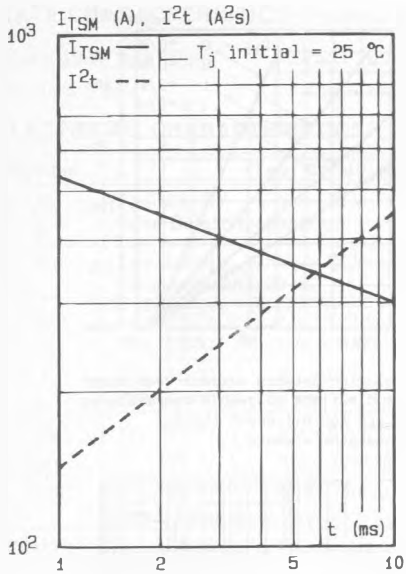


Fig. 7 - Non repetitive surge peak on-state current for a sinusoidal pulse with width : $t \leq 10$ ms, and corresponding value of I^2t .

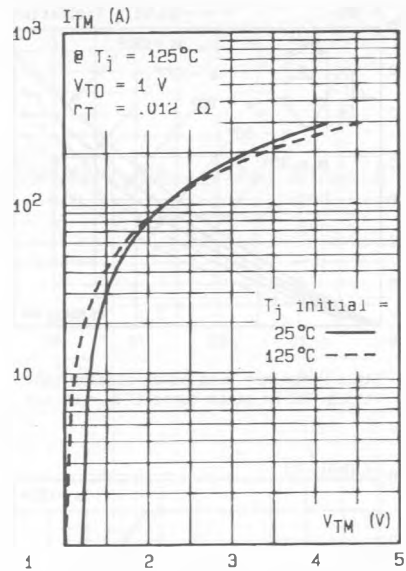


Fig.8 - On-state characteristics (maximum values) .